1 Package summary

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<td>actual quantity of termination</td>
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2 Package outline

Figure 1. Package outline FOWLP249 (SOT2003-1)
3 Soldering

Figure 2. Reflow soldering footprint part1 for FOWLP249 (SOT2003-1)
Reflow soldering footprint part2 for FOWLP249 (SOT2003-1)

PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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Figure 4. Reflow soldering footprint part3 for FOWLP249 (SOT2003-1)
Figure 5. Package outline note FOWLP249 (SOT2003-1)
4 Legal information

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